

PS7200H-1A

4-PIN SOP, 2.2 Ω LOW ON-STATE RESISTANCE 1-ch Optical Coupled MOS FET

DESCRIPTION

The PS7200H-1A is a low on-state capacitance solid state relay containing a GaAs LED on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for high-frequency signal control, due to its low $C \times R$, low on-state resistance, and low off-state leakage current.

FEATURES

- Low C × R (C × R = 9.2 pF Ω)
- Low on-state resistance (Ron = 2.2 Ω TYP.)
- Low output capacitance (Cout = 4.2 pF TYP.)
- Low off-state leakage current (ILoff = 0.03 nA TYP.)
- High-speed turn-on time (ton = 0.04 ms TYP.)
- 1 channel type (1 a output)
- · Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- High isolation voltage (BV = 1 500 Vr.m.s.)
- · Low offset voltage
- Ordering number of taping product : PS7200H-1A-E3, E4: 900 pcs/reel

: PS7200H-1A-F3, F4: 3 500 pcs/reel

<R>

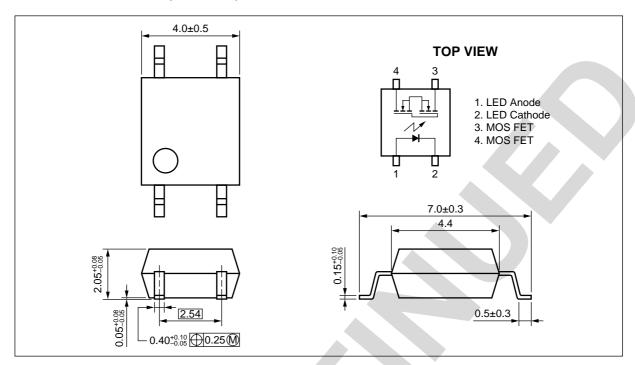
· Pb-Free product

APPLICATIONS

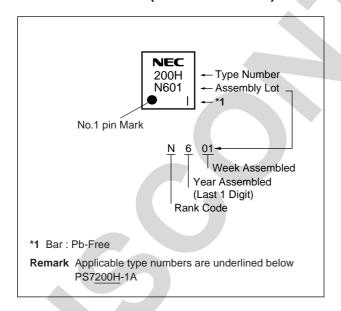
Measurement equipment

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PACKAGE DIMENSIONS (UNIT: mm)



<R> MARKING EXAMPLE (LASER MARKING)



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style
PS7200H-1A	PS7200H-1A-A	Pb-Free	Magazine case 100 pcs
PS7200H-1A-E3	PS7200H-1A-E3-A		Embossed Tape 900 pcs/reel
PS7200H-1A-E4	PS7200H-1A-E4-A		
PS7200H-1A-F3	PS7200H-1A-F3-A		Embossed Tape 3 500 pcs/reel
PS7200H-1A-F4	PS7200H-1A-F4-A		

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current (DC)	lF	50	mA	
	Reverse Voltage	VR	5.0	V	
	Power Dissipation	Po	50	mW	
	Peak Forward Current*1	IFP	1	Α	
MOS FET Break Down Voltage		VL	40	V	
	Continuous Load Current	lι	160	mA	
	Pulse Load Current*2 (AC/DC Connection)	Ігь	320	mA	
	Power Dissipation	Po	100	mW	
Isolation Voltage*3		BV	1 500	Vr.m.s.	
Total Power Dissipation		Рт	150	mW	
Operating Ambient Temperature		TA	-40 to +85	°C	
Storage Temperature		Tstg	-40 to +100	°C	

^{*1} PW = 100 μ s, Duty Cycle = 1%

^{*2} PW = 100 ms, 1 shot

^{*3} AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together.

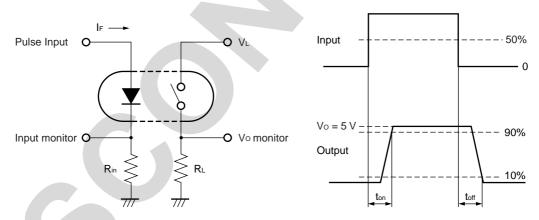
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	
LED Operating Current	lF	2	10	20	mA	
LED Off Voltage	VF	0		0.5	V	

ELECTRICAL CHARACTERISTICS (TA = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	lR	V _R = 5 V			5.0	μА
MOS FET	Off-state Leakage Current	Loff	V _D = 40 V		0.03	10	nA
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		4.2		pF
Coupled	LED On-state Current	IFon	IL = 160 mA			2.0	mA
	On-state Resistance	Ron1	IF = 10 mA, IL = 50 mA		2.2	3.5	Ω
		Ron2	$I_F = 10 \text{ mA}, I_L = 160 \text{ mA}, t \le 10 \text{ ms}$		2.2	3.5	
	Turn-on Time*1, 2	ton	IF = 10 mA, Vo = 5 V, RL = 500 Ω ,		0.04	0.5	ms
	Turn-off Time*1, 2	t off	PW ≥ 10 ms		0.25	1.0	
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10 ⁹			Ω
	Isolation Capacitance	CI-O	V = 0 V, f = 1 MHz		0.4		pF

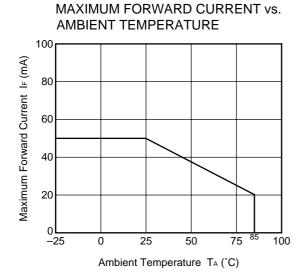
*1 Test Circuit for Switching Time

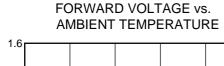


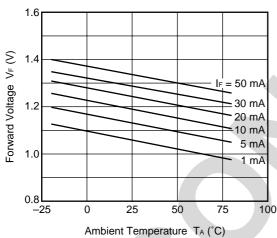
*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.

Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

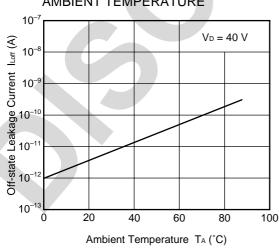
TYPICAL CHARACTERISTICS (Ta = 25°C, unless otherwise specified)



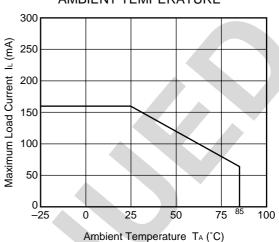




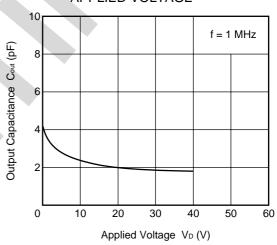
OFF-STATE LEAKAGE CURRENT vs. AMBIENT TEMPERATURE



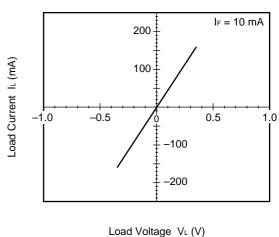
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



OUTPUT CAPACITANCE vs. APPLIED VOLTAGE

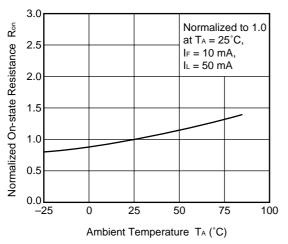


LOAD CURRENT vs. LOAD VOLTAGE

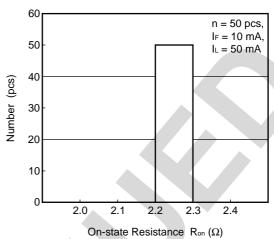


Remark The graphs indicate nominal characteristics.

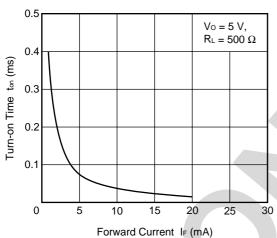
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



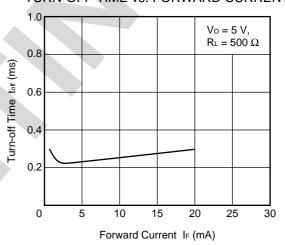
ON-STATE RESISTANCE DISTRIBUTION



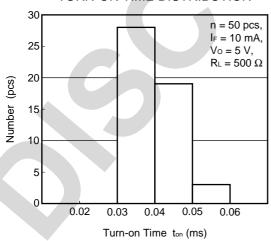
TURN-ON TIME vs. FORWARD CURRENT



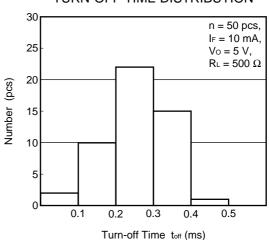
TURN-OFF TIME vs. FORWARD CURRENT



TURN-ON TIME DISTRIBUTION

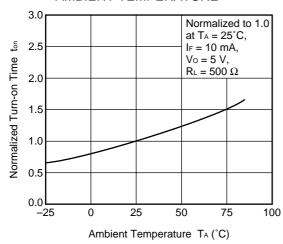


TURN-OFF TIME DISTRIBUTION



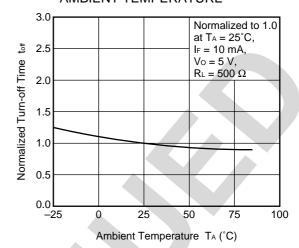
Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

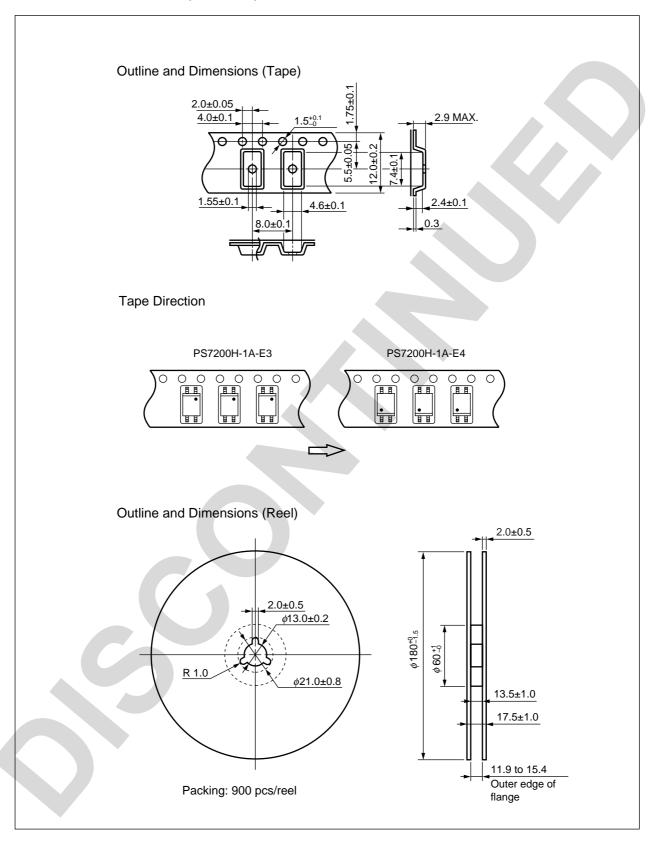


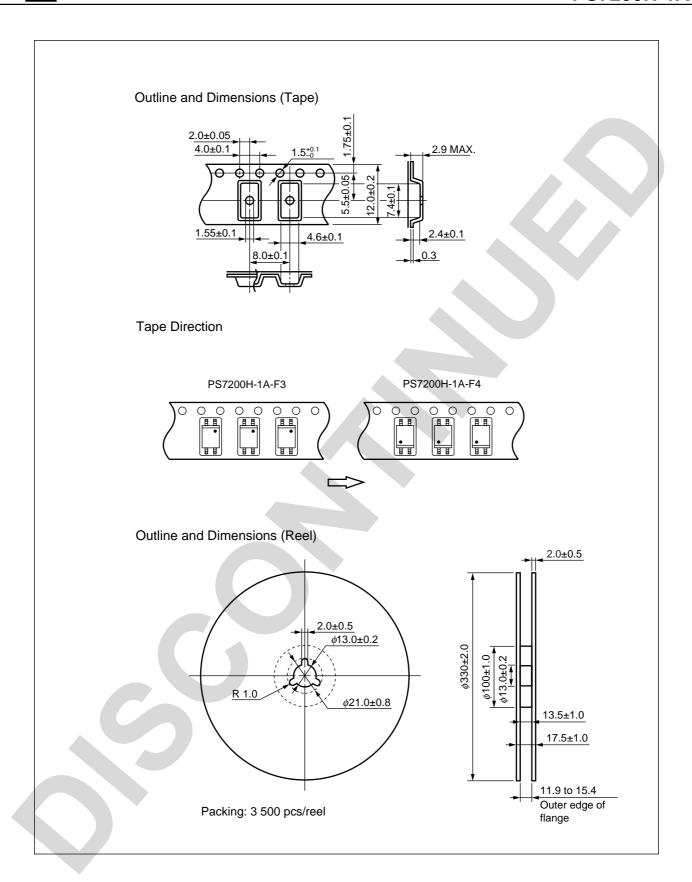
Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



TAPING SPECIFICATIONS (UNIT: mm)





RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

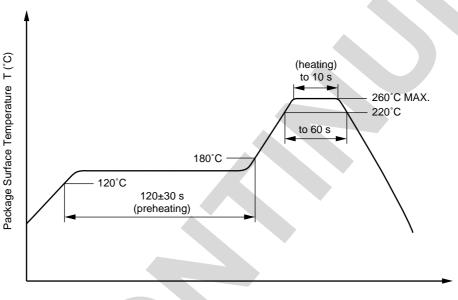
Time of peak reflow temperature
 Time of temperature higher than 220°C
 10 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

Preheating conditions
 120°C or below (package surface temperature)

• Number of times One

Flux
 Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

Peak temperature (lead part temperature)
 Time (each pins)
 350°C or below
 3 seconds or less

Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.



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M8E 02.11-1

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

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